EAST - [10698940.wsp:1]

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Drafts
BRS: semiconductor and packag$3 and wiring near substrate and ((via near hole) with (
Pending
Active
L1: (546) semiconductor and packag$3 and wiring near substrate and (chip$1 die dice) and (via hol...
L2: (438) semiconductor and packag$3 and wiring near substrate and (chip$1 die dice) and (via hol...
L3: (46) semiconductor and packag$3 and wiring near substrate and (chip$1 die dice) and (via hole...
L4: (231) semiconductor and packag$3 and wiring near substrate and (chip$1 die dice) and (via hol...
L6: (7) semiconductor and packag$3 and wiring near substrate and ((chip$1 die dice) with (through...
L7: (7) semiconductor and packag$3 and wiring near substrate and ((chip$1 die dice) with (through...
L5: (149) semiconductor and packag$3 and wiring near substrate and ((chip$1 die dice) with (via h...
L8: (154) semiconductor and packag$3 and ((via near hole) with (through with chip))
L9: (13) semiconductor and packag$3 and ((via near hole) with (through near chip))
L10: (0) semiconductor and packag$3 and ((via near hole) with (pass$2 near through near chip))
L11: (0) packag$3 and ((via near hole) with (pass$2 near through near chip))
L12: (21209) packag$3 and grind$3
L13: (117) packag$3 and grind$3 and (chip$1 die dice) and interlayer near insulat$3
L14: (126) packag$3 and grind$3 and interlayer near insulat$3
L15: (513) grind$3 and interlayer near insulat$3
L16: (1) "20020127839"
L17: (1) "20010008794"
L18: (1) "20010004130"
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DBs   US-PGPUB; USPAT; EPO;   Plurals

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"20010004130"

BRS form   S&R form   Image   Text   HTML

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Ref
1			US 20010004130 A1	20010621	13	Semiconductor device and production method thereof	257/686	257/E23.178; 257/E25.011	

rd   Inbox - Micr   eDAN 1.6.1   EAST - [106...   EAST Brow   EAST Brow